

# DDR4 SERIES



## Features:

- Smaller pitch and lower operating voltage
- Supports faster data rates
- Reduced product width
- Various pin tail lengths for PCB thickness

## Overview:

- Complies to new interface standard JEDEC POD12
- Nylon 9T halogen free housing for reflow process
- Matte tin plating on contact soldering area for lead-free soldering process
- Supports module variants in UDIMM, RDIMM and LRDIMM
- Allows module seating plane of 2.4mm Max
- Accepts module thickness of 1.4mm

## Applications:

- Storage
- Servers
- Desktops
- Industrial Computers



## Ordering Information:

**DDR4 - 288 - X - XX - X - X - X - X**

<p><b>Termination</b></p> <p>V TH type</p> <p>S SMT type</p>	<p><b>Dip Options (Dim A, Dim B, Dim C)</b></p> <table border="0"> <tr> <td style="background-color: #90EE90; padding: 2px;">*</td> <td>TH Type</td> <td>01 2.10mm, 3.94mm, 1.57mm</td> </tr> <tr> <td></td> <td></td> <td>02 2.67mm, 3.94mm, 1.57mm</td> </tr> <tr> <td></td> <td></td> <td>03 3.95mm, 4.60mm, 2.36mm</td> </tr> <tr> <td></td> <td></td> <td>04 3.18mm, 4.60mm, 2.36mm</td> </tr> <tr> <td style="background-color: #90EE90; padding: 2px;">**</td> <td>SMT Type</td> <td>01 3.94mm, 1.57mm ***</td> </tr> <tr> <td></td> <td></td> <td>02 3.94mm, 1.57mm</td> </tr> <tr> <td></td> <td></td> <td>03 4.60mm, 2.36mm ***</td> </tr> <tr> <td></td> <td></td> <td>04 4.60mm, 2.36mm</td> </tr> <tr> <td></td> <td></td> <td>05 2.00mm, 1.57mm ***</td> </tr> <tr> <td></td> <td></td> <td>06 2.00mm, 1.57mm</td> </tr> </table>	*	TH Type	01 2.10mm, 3.94mm, 1.57mm			02 2.67mm, 3.94mm, 1.57mm			03 3.95mm, 4.60mm, 2.36mm			04 3.18mm, 4.60mm, 2.36mm	**	SMT Type	01 3.94mm, 1.57mm ***			02 3.94mm, 1.57mm			03 4.60mm, 2.36mm ***			04 4.60mm, 2.36mm			05 2.00mm, 1.57mm ***			06 2.00mm, 1.57mm	<p><b>Latch Option</b></p> <p>Blank Small</p> <p>F Big</p> <p><b>Packing Code</b></p> <p>T Soft tray</p> <p>H Hard tray (only SMT type)</p> <p><b>Contact Area Plating</b></p> <p>0 Gold flash</p> <p>1 15µ" gold</p> <p>2 20µ" gold</p> <p>3 30µ" gold</p> <p>4 3µ" gold over 12µ" PdNi</p> <p>5 3µ" gold over 27µ" PdNi</p> <p><b>Color of Housing/Latch</b></p> <p>1 Black/Black</p> <p>2 Black/Natural</p> <p>3 Natural/Black</p> <p>4 Natural/Natural</p> <p>5 Blue/Natural</p> <p>6 Green/Natural</p> <p>7 Blue/Blue</p>	<p><b>* TH Type Note:</b></p> <p>Dim A = Pin tail length</p> <p>Dim B = Board lock length</p> <p>Dim C = Recommended PCB thickness</p> <p><b>** SMT Type Note:</b></p> <p>Dim A = Board lock length</p> <p>Dim B = Recommended PCB thickness</p> <p><b>*** With Mylar for Pick and Place assembly equipment</b></p>
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To learn more about DDR4 connectors:

web: [amphenolcanada.com](http://amphenolcanada.com)

email: [sales@amphenolcanada.com](mailto:sales@amphenolcanada.com)

## Technical Characteristics:

Mechanical	
<b>Insertion Force</b>	10.88Kgf max.
<b>Withdrawal Force</b>	14gf min. (per contact pair)
<b>Retention Force</b>	Contact: 0.30Kgf min. Boardlock: 1.36Kgf min.
<b>Durability</b>	Contact resistance: $\Delta R$ : 10m $\Omega$ max. after test
<b>Vibration, Mechanical Shock</b>	No physical damage Discontinuity < 1 $\mu$ s Contact resistance: $\Delta R$ : 10m $\Omega$ max. after test
<b>Reseating</b>	No damage
<b>Latch Overstress Force</b>	3.5kg min. force held for 10s with no damage
<b>Latch Actuation Force</b>	The force to fully actuate the latch open shall be 4.5kgf max. per latch
<b>Module Rip Out Force</b>	9.1kgf min. retention force of the module in connector with no damage
<b>Retention of Connector to PCB</b>	No lifting of connector from applicable PCB
<b>Insertion Force of Connector into PCB</b>	Total insertion force to be 6.8kgf max.

Electrical	
<b>Voltage Rating</b>	30V AC (RMS)/DC
<b>Current Rating</b>	0.7 Amps/pin max.
<b>Low Level Contact Resistance</b>	10m $\Omega$ max. initial $\Delta R$ : 10m $\Omega$ max. after test
<b>DWV</b>	No breakdown
<b>Insulation Resistance</b>	1000 M $\Omega$ min.

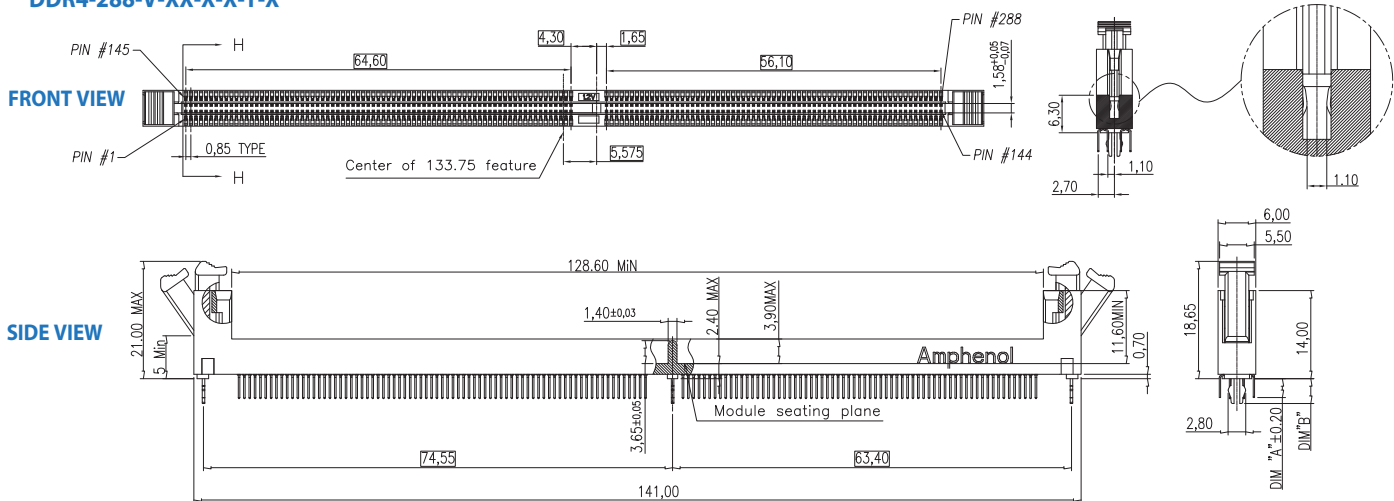
Materials	
<b>Insulator</b>	High temp. thermal plastic, UL94V-0, Color-option
<b>Contacts</b>	Copper alloy a) Gold flash or b) 15 microinches minimum of gold or c) 30 microinches minimum of gold
<b>Solder Area</b>	Tin or matte tin plating
<b>Underplate</b>	Nickel plating over all
<b>Boardlock</b>	Copper alloy
<b>Solder Area</b>	Tin plating
<b>Underplate</b>	Nickel plating overall

Environmental	
<b>Solderability</b>	Solder coverage: 95% min.
<b>Resistance to Soldering Heat</b>	Visual: no damage or discoloration of connector materials
<b>Temperature Life, Thermal Shock</b>	Contact resistance: $\Delta R$ : 10m $\Omega$ max. after test
<b>Cycling Temperature and Humidity</b>	Contact resistance: $\Delta R$ : 10m $\Omega$ max. after test DWV: No breakdown at 500VAC Insulation Resistance: 1000 M $\Omega$ min.
<b>Temperature Rise</b>	Temperature rise: 30°C max.
<b>Mixed Flowing Gas, Thermal Disturbance, Salt Spray</b>	Contact resistance: $\Delta R$ : 10m $\Omega$ max. after test

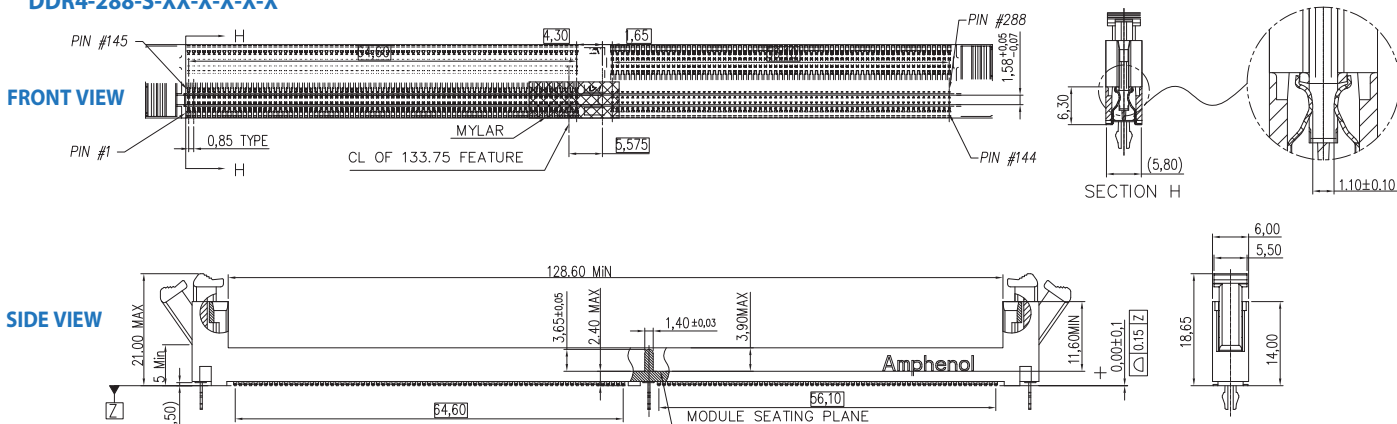
## Dimensions:

### DDR4-288-V-XX-X-X-T-X

All drawings are measured in millimeters (mm).



### DDR4-288-S-XX-X-X-X-X



\* Please visit [amphenolcanada.com](http://amphenolcanada.com) to find drawings for other products in this series.

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email: [sales@amphenolcanada.com](mailto:sales@amphenolcanada.com)